



Subject: Motorola PRODUCT BULLETIN 4455

TITLE: COMPLETE CONVERSION OF THYRISTOR FULLPAK TO NI PLATED HEATSINKS

EFFECTIVE DATE: 11-FEB-99

AFFECTED CHANGE CATEGORIES

AFFECTED PRODUCT DIVISIONS
POWER PRODUCTS DIV

ADDITIONAL RELIABILITY DATA: None

Ref:

SAMPLES: No

Ref:

For any questions concerning this notification:

REFERENCE:DAVE CULBERTSON

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DISCLAIMER:

MOTOROLA CONSIDERS THIS CHANGE APPROVED UNLESS SPECIFIC CONDITIONS
OF ACCEPTANCE ARE PROVIDED IN WRITING. TO DO SO, CONTACT YOUR LOCAL
MOTOROLA SALES OFFICE.

GPCN FORMAT: CUSTOMER

DO NOT REPLY TO THIS MESSAGE.

PRODUCT BULLETIN

ISSUE DATE: 10-Feb-1999

NOTIFICATION #:4455

EFFECTIVE DATE: 11-Feb-1999

ISSUING DIVISION:PHX-PPD

DESCRIPTION AND PURPOSE

Thyristor TO220's have been using Ni heatsinks for some time. This change is to complete the conversion of Thyristor FulPak from Cu to Ni plated heatsinks. All electrical, thermal characterization, and reliability tests are complete; this change supports initiatives for continuous improvement of product.

FILE FORMAT: ASCII TEXT

FONT - Courier

SIZE - 12 Point

LINE - 70 characters/line

PAGE - 55 lines/page

PAGEBREAK CHARACTER - ^L (Control L)

AFFECTED DEVICE LIST (WITHOUT SPECIALS)

MAC15A10FP	, MAC15A6FP	, MAC15A8FP	, MAC210A10FP
MAC210A8FP	, MAC212A10FP	, MAC212A6FP	, MAC212A8FP
MAC218A10FP	, MAC218A6FP	, MAC223A10FP	, MAC223A6FP
MAC223A8FP	, MAC228A10FP	, MAC229A8FP	, MAC320A8FP
MCR218-10FP	, MCR218-6FP	, MCR218-8FP	, MCR225-10FP
MCR225-2FP	, MCR225-8FP	, T2500DFP	